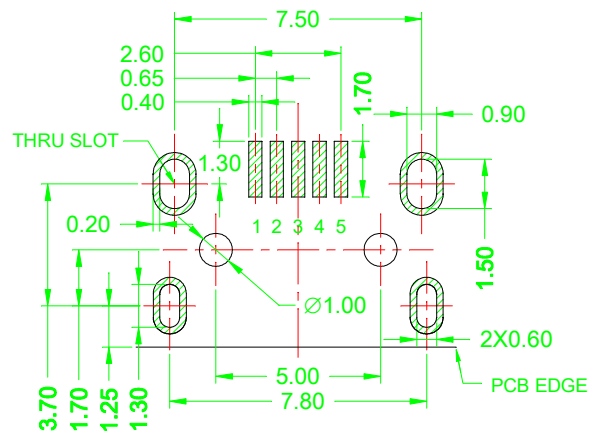
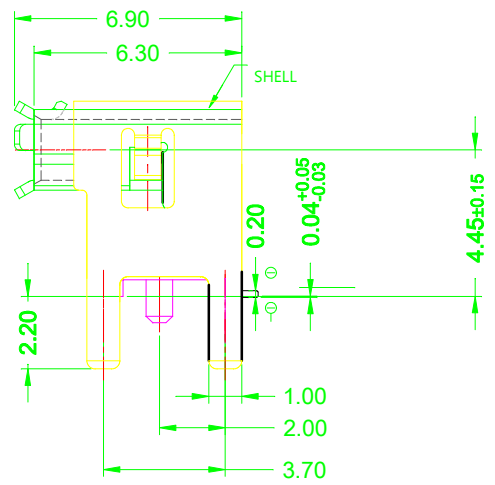
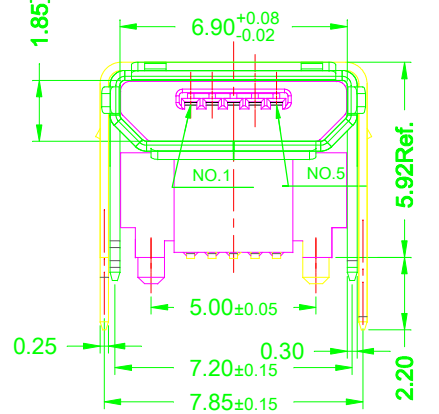


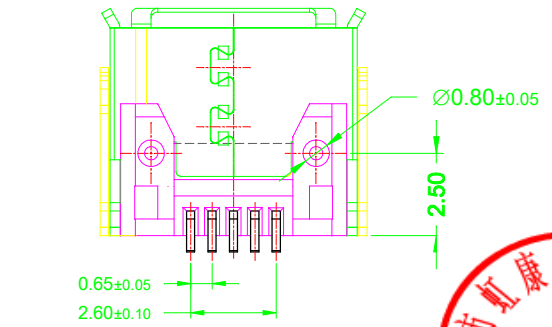
MUB5B-01XXB448

Contact Finish:
 00: Material 10: 10u"Gold
 01: G/F 15: 15u"Gold
 05: 5u"Gold 30: 30u"Gold

- MATERIAL**
 HOUSING: LCP,UL94V-0,BLACK
 CONTACT: COPPER ALLOY,T=0.20
 SHELL: STAINLESS STEEL,T=0.3
 COVER: STAINLESS STEEL,T=0.25
- FINISH**
 CONTACT: 50U" MIN NICKEL UNDERPLATING OVERALL
 GOLD PLATING SELECTIVE ON CONTACT AREA
 50U" MIN TIN PLATING ON SOLDER TAIL
 SHELL: 40U" MIN NICKEL UNDERPLATING OVERALL
 COVER: 40U" MIN NICKEL UNDERPLATING OVERALL
- ELECTRICAL**
 CURRENT: 1.0A
 VOLTAGE: 30V
 CONTACT RESISTANCE: 50 MILLIOHMS MAX.
 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC
 INSULATION RESISTANCE: 100 MEGOHMS MIN.
- MECHANICAL**
 MATING FORCE: 35N MAX.
 UNMATING FORCE: 10N MIN,INITIAL.
 8~20N AFTER 10000 CYCLES.
 DURABILITY: 10000 CYCLES
- PRODUCT NO. DESCRIPTION:**



RECOMMENDED PCB LAYOUT
 (PCB T=1.60 mm)



| 尺寸 | 允许公差 |
|-----|--------|
| X | ±0.50 |
| X | ±0.20 |
| XX | ±0.10 |
| XXX | ±0.03 |
| 角度 | ±1.00° |

深圳市虹康科技有限公司

| | | | |
|-------|--|----------------------------|-----------|
| 图纸类型 | | 图纸名称: MICRO USB 5P B-F SMT | |
| 产品工程图 | | CL=4.45(长脚2.2, 有边) | |
| 设计 | | 产品料号 | SHK-20163 |
| 审核 | | 视图 | 版号: A/0 |